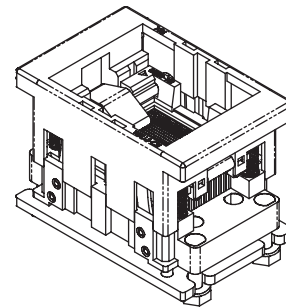
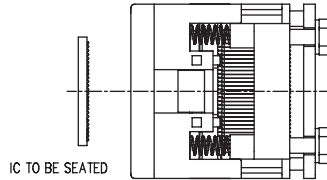
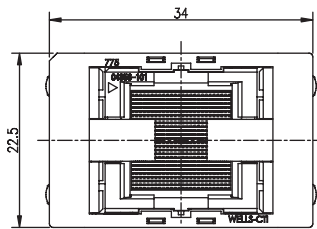
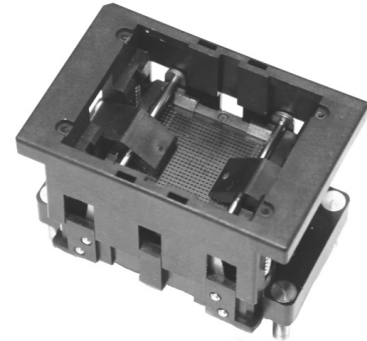




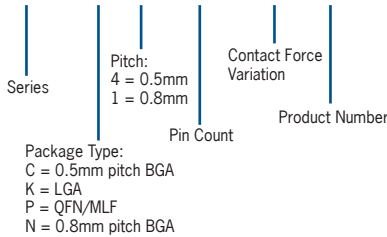
775 SERIES OPEN TOP CSP

- 0.5mm and 0.8mm pitch
- Compression surface mount
- High performance/low cost achieved through use of carrier loaded stamped contact
- Z-axis compliant buckling beam contact supports any type solder ball shape and composition
- Compact outline and low actuation force achieved through use of innovative latching mechanism



DESCRIPTION & ORDERING INFORMATION

775 X X XXX - X XX



MATERIALS & SPECIFICATIONS

- Body Materials: PES, PEI, LCP or Equivalent
- Contact Material: Beryllium Copper Alloy
- Contact Plating: Gold
- Contact Force: 13 gram average
- Contact Resistance: 200~300 mΩ
- Temperature Rating: 150°C
- Durability: 10,000 cycles min.

Pitch e (mm)	Package Size (mm)	Pin Matrix.	Max. Pin Count	Ball Dia. (mm)	Ball Height (mm)	Part Number
0.5	5X5	8X8	32	QFN	0	775P4032-XXX
	7X7	12X12	48	QFN	0	775P4048-XXX
	6X9	11X17	187	0.30	0.15min.	775C4187-XXX
	7X7	14X14	196	0.30	0.15min	775C4196-XXX
	7X7	14X14	196	LGA	0	775K4196-XXX
	8X8	14X14	196	0.30	0.15min	775C4196-XXX
	6X10	11X19	209	0.30	0.21	775C4209-XXX
	11X11	15X21	315	0.309	0.23	775C4315-XXX
	11X13	15X21	315	0.309	0.23	775C4315-XXX
	8X12	15X22	330	0.30	0.21	775C4330-XXX
	11x13	20x24	350	0.30	0.21	775C4350-XXX
	12X12	22X22	350	0.30	0.21	775C4350-XXX
	10X15	19X29	350	0.30	0.25	775C4350-XXX
14X14	26X26	356	0.30	0.21	775C4356-XXX	
0.8	15X15	17X17	289	0.30	0.15	775N1289-XXX